

Dual N-channel MOSFET (common drain)

ELM18822BA-S

■General description

ELM18822BA-S uses advanced trench technology to provide excellent $R_{ds(on)}$ and low gate charge.

■Features

- $V_{ds}=20V$
- $I_d=7A$ ($V_{gs}=10V$)
- $R_{ds(on)} < 21m\Omega$ ($V_{gs}=10V$)
- $R_{ds(on)} < 24m\Omega$ ($V_{gs}=4.5V$)
- $R_{ds(on)} < 32m\Omega$ ($V_{gs}=2.5V$)
- $R_{ds(on)} < 50m\Omega$ ($V_{gs}=1.8V$)

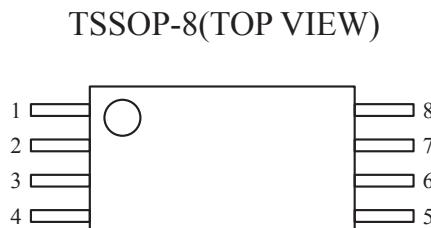
■Maximum absolute ratings

Parameter	Symbol	Limit	Unit	Note
Drain-source voltage	V_{ds}	20	V	
Gate-source voltage	V_{gs}	± 12	V	
Continuous drain current	I_d	7.0	A	1
		5.7		
Pulsed drain current	I_{dm}	30	A	2
Power dissipation	P_d	1.50	W	1
		0.96		
Junction and storage temperature range	T_j, T_{stg}	-55 to 150	°C	

■Thermal characteristics

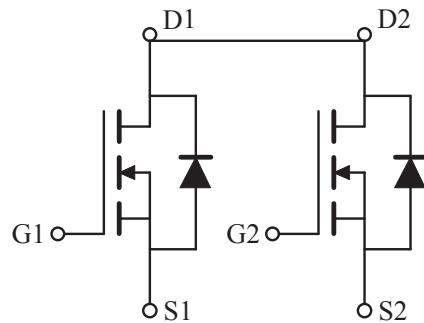
Parameter		Symbol	Typ.	Max.	Unit	Note
Maximum junction-to-ambient	$t \leq 10s$	$R_{\theta ja}$	63	83	°C/W	1
Maximum junction-to-ambient	Steady-state		101	130	°C/W	
Maximum junction-to-lead	Steady-state	$R_{\theta jl}$	64	83	°C/W	3

■Pin configuration



Pin No.	Pin name
1	DRAIN1/DRAIN2
2	SOURCE1
3	SOURCE1
4	GATE1
5	GATE2
6	SOURCE2
7	SOURCE2
8	DRAIN1/DRAIN2

■Circuit



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■Electrical characteristics

T_a=25°C

Parameter	Symbol	Condition		Min.	Typ.	Max.	Unit	
STATIC PARAMETERS								
Drain-source breakdown voltage	BVdss	Id=250μA, Vgs=0V		20			V	
Zero gate voltage drain current	Idss	Vds=16V, Vgs=0V	Tj=55°C			1	μA	
						5		
Gate-body leakage current	Igss	Vds=0V, Vgs=±10V				100	nA	
Gate-source breakdown voltage	BVgso	Vds=0V, Ig=±250μA		±12			V	
Gate threshold voltage	Vgs(th)	Vds=Vgs, Id=250μA		0.5	0.8	1.0	V	
On state drain current	Id(on)	Vgs=4.5V, Vds=5V		30			A	
Static drain-source on-resistance	Rds(on)	Vgs=10V, Id=7A			16.4	21.0	mΩ	
		Tj=125°C			23.0	28.0		
		Vgs=4.5V, Id=6.6A			19.0	24.0	mΩ	
		Vgs=2.5V, Id=5.5A			25.0	32.0	mΩ	
		Vgs=1.8V, Id=2A			36.0	50.0	mΩ	
Forward transconductance	Gfs	Vds=5V, Id=7A			24		S	
Diode forward voltage	Vsd	Is=1A, Vgs=0V			0.7	1.0	V	
Max. body-diode continuous current	Is					2.5	A	
DYNAMIC PARAMETERS								
Input capacitance	Ciss	Vgs=0V, Vds=10V, f=1MHz			630		pF	
Output capacitance	Coss				164		pF	
Reverse transfer capacitance	Crss				137		pF	
Gate resistance	Rg	Vgs=0V, Vds=0V, f=1MHz			1.5		Ω	
SWITCHING PARAMETERS								
Total gate charge	Qg	Vgs=4.5V, Vds=10V, Id=7A			9.3		nC	
Gate-source charge	Qgs				0.6		nC	
Gate-drain charge	Qgd				3.6		nC	
Turn-on delay time	td(on)	Vgs=5V, Vds=10V Rl=1.4Ω, Rgen=3Ω			5.7		ns	
Turn-on rise time	tr				11.5		ns	
Turn-off delay time	td(off)				31.5		ns	
Turn-off fall time	tf				9.7		ns	
Body diode reverse recovery time	trr	If=7A, dl/dt=100A/μs			15.2		ns	
Body diode reverse recovery charge	Qrr	If=7A, dl/dt=100A/μs			6.3		nC	

NOTE :

1. The value of R_{θja} is measured with the device mounted on 1in² FR-4 board of 2oz. Copper, in still air environment with T_a=25°C. The value in any given applications depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.
2. Repetitive rating, pulse width limited by junction temperature.
3. The R_{θja} is the sum of the thermal impedance from junction to lead R_{θjl} and lead to ambient.
4. The static characteristics in Figures 1 to 6 are obtained using 80μs pulses, duty cycle 0.5%max.
5. These tests are performed with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_a=25°C. The SOA curve provides a single pulse rating.



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■ Typical electrical and thermal characteristics

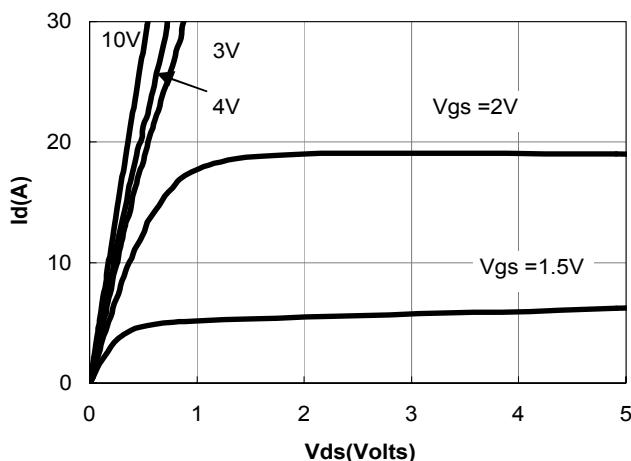


Figure 1: On-Regions Characteristics

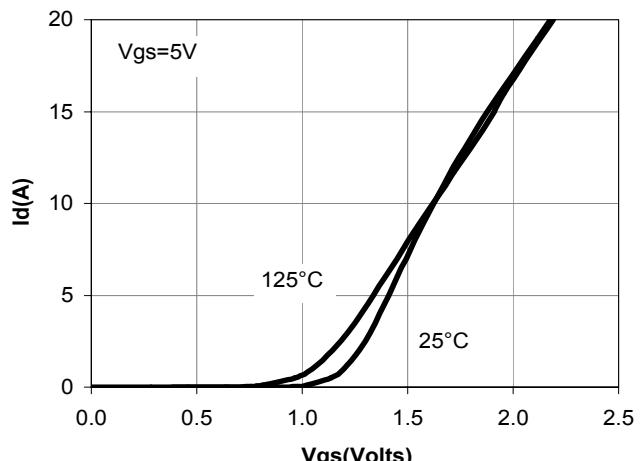


Figure 2: Transfer Characteristics

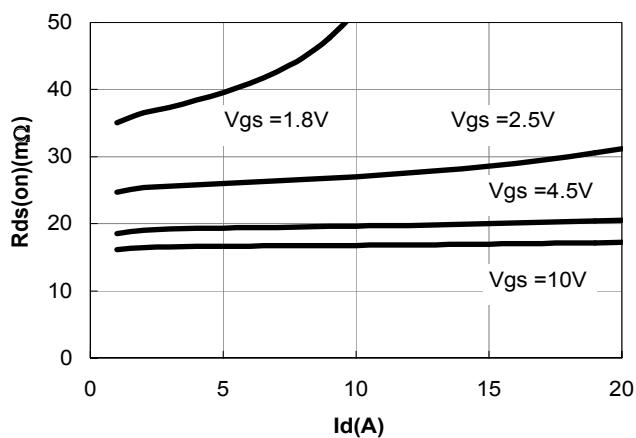


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

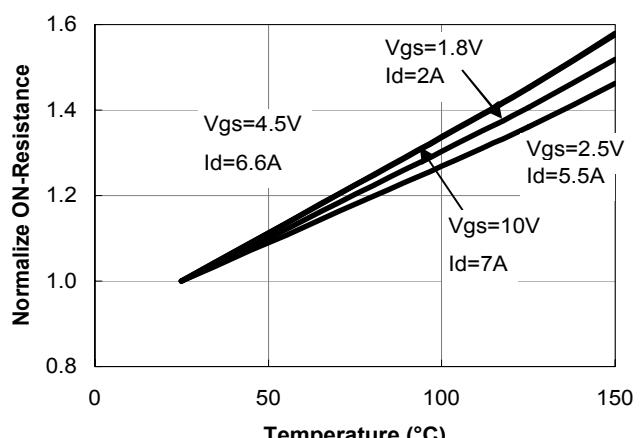


Figure 4: On-Resistance vs. Junction Temperature

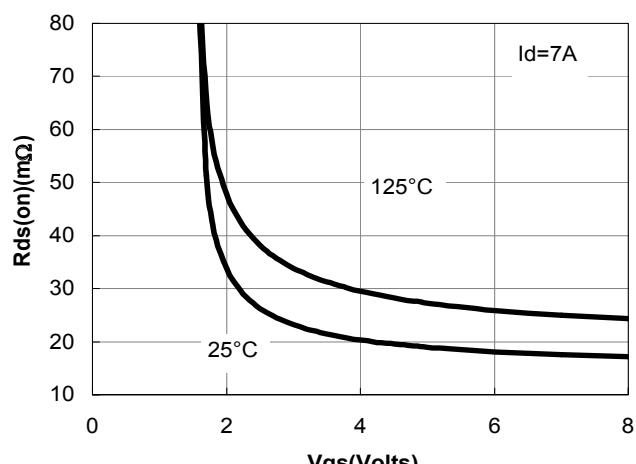


Figure 5: On-Resistance vs. Gate-Source Voltage

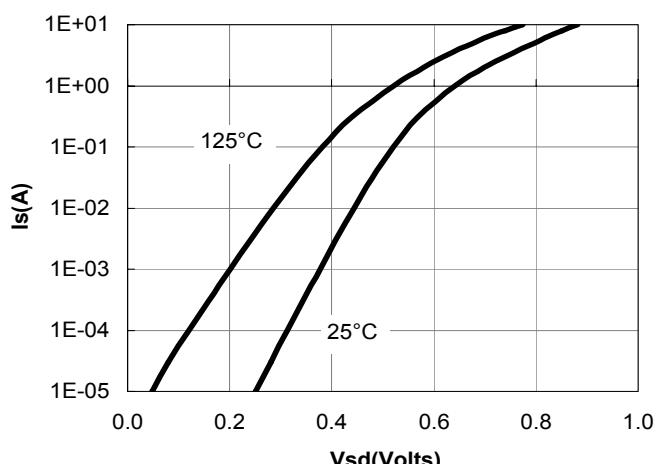


Figure 6: Body-Diode Characteristics

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